

CLAIMS

1. A multi layer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, characterized in that
 - a plurality of plain layers are formed as said conductor layers; and
 - mesh holes are formed in said plurality of plain layers so that at least part of the mesh holes overlay on one another.
2. A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, characterized in that
 - a plain layer serving as a conductor layer is formed at least one side of said core substrate;
 - a plain layer is formed out of at least one of the conductor layers formed between said interlayer resin insulating layers; and
 - mesh holes are formed in the plain layer of said core substrate and the plain layer between said interlayer resin insulating layers so that at least part of the mesh holes overlay on one another.
3. The multilayer build-up wiring board according to claim 1 or 2, characterized in that
 - a diameter of each of said mesh holes is set at 75 to 300 μm and a distance between the mesh holes is set at 100 to 1500 μm .
4. A multi layer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, provided with a chip mount region on which a chip is mounted on an outermost layer and having the conductor layers connected to each other by via holes, respectively characterized in that

mesh holes are provided in plain layers formed as said conductor layers, and lands of through holes or the via holes and the via holes are provided in at least part of mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

5. A multi layer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, provided with a chip mount region on an outermost layer and having the conductor layers connected to each other by via holes, respectively, characterized in that

mesh holes are provided in plain layers formed as said conductor layers, and lands of the via holes are provided in at least part of mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

6. A multilayer build-up wiring board obtained by alternately providing interlayer resin insulating layers and conductor layers, provided with a chip mount region on an outermost layer characterized in that

mesh holes are provided in plain layers formed as said conductor layers, and solid conductor layers are provided in at least part of mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

7. A multilayer build-up wiring board wherein interlayer resin insulating layers and conductor layers are alternately provided on a substrate having through holes and a chip mount region for mounting a chip is provided on an outermost layer, characterized in that

mesh holes are provided in plain layers formed as said conductor layers, and lands of the through holes are provided in at least part of mesh holes in a region facing said chip mount region through the interlayer resin insulating layers.

8. A multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, respectively, the multilayer wiring layer formed on a core substrate, characterized in that

one of said via holes is formed out of a plurality of wiring paths.

9. A multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, respectively, the multilayer wiring layer formed on a core substrate, characterized in that one of said via holes is formed out of two wiring paths.

10. A multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, respectively, the multilayer wiring layer formed on a core substrate, said conductor layers electrically connected to conductor layers on back side of the core substrate by through holes formed in the core substrate, respectively, characterized in that

a plurality of wiring paths are provided in each of the through hole in said core substrate; and

via holes consisting of a plurality of wiring paths each connected to each of said wiring paths of said through hole are provided right on said through holes in which said plurality of wiring paths are provided .

11. A multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, the multilayer wiring layer formed on both sides of a core substrate, conductor layers of the both sides of said core substrate electrically connected to one another by through holes formed in the core substrate, characterized in that

a plurality of wiring paths are provided in each of the through holes in said core substrate; and

via holes consisting of a plurality of wiring paths each connected to each of said wiring paths of said through hole are provided right on said through holes in which said plurality of wiring paths are provided .

12. A multilayer build-up wiring board having a multilayer wiring layer, wherein interlayer resin insulating layers and conductor layers are alternately provided and the conductor layers are connected to each other by via holes, the multilayer wiring layer formed on both sides of a core substrate, conductor layers of the both sides of said core substrate electrically connected to one another by through holes formed in the core substrate, characterized in that

a filler is filled in the through holes of said core substrate and a conductor layer covering an exposed surface of the filler from the through holes is formed in the through hole;

the through holes and the conductor layers are divided into a plurality of parts, respectively; and

via holes consisting of wiring paths connected to the divided parts of the conductor layers, respectively, are provided right on the through holes covered with said divided parts of the conductor layers.

13. A wiring board having a conductor circuit including a conductor layer of two-layer structure in which a second metal film thinner than a first metal film is provided on said first metal film, characterized in that

sides of the second metal film forming said conductor layer protrude outside compared with sides of said first metal film.

14. A multilayer build-up wiring board having a structure in which at least one resin insulating layer and at least one conductor circuit are formed on a resin substrate, characterized in that

at least one layer of said conductor circuit includes a conductor layer of two layer structure in which a second metal film thinner than a first metal film is provided on said first metal film; and

sides of the second metal film forming said conductor layer protrude outside compared with sides of said first metal film.